Electronic Version
Stylesheet Version v1.1.1

Claims

[c1] A printed circuit board having a plurality of tracks for operably coupling electrical signals to a plurality of contact points of at least one integrated circuit package device, wherein the plurality of contact points includes an inner portion of contact points and an outer portion of contact points, the printed circuit board comprising at least one of the following:
(i) a majority of power supply contacts configured substantially in an extremity of said outer portion;
(ii) a majority of timing or frequency contacts configured substantially in said outer portion ; and
(iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

[c2] The printed circuit board according to Claim 1, wherein ground contacts are further provided along a bisectional axis, through said outer portion to facilitate a ground path from outside an area of the integrated circuit package device to said inner portion.

[c3] The printed circuit board according to Claim 1, wherein said inner portion is formed substantially of ground con-

tact points to effect a ground plane.

[c4] The printed circuit board according to Claim 1, wherein, for one or more signals associated with (i) to (iii), all of said respective contacts of said integrated circuit package device are configured in the respective manner described in one or more of (i) to (iii)

[c5] An electrical or electronic device comprising the integrated circuit package device according to claim 1.

[c6] The printed circuit board according to claim 1 further comprising at least one ground contact configured substantially in said inner portion.

[c7] The printed circuit board according to claim 1 wherein the inner portion and the outer portion are two distinct regions separated by a space.

[c8] An arrangement of a plurality of contact points in one of an integrated circuit package device and a printed circuit board wherein the plurality of contact points includes an inner portion of said contact points and an outer portion of said contact points, and at least one of the following:
(i) a majority of power supply contacts is configured substantially in an extremity of said outer portion;
(ii) a majority of timing or frequency contacts is configured substantially in said outer portion; and

(iii) a majority of data or high speed signal contacts is configured substantially in an inner side of said outer portion.

[c9] A printed circuit board according to claim 1 comprising two or more of the following:
(i) a majority of power supply contacts configured substantially in an extremity of said outer portion;
(ii) a majority of timing or frequency contacts configured substantially in said outer portion; and
(iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

[c10] A printed circuit board according to claim 9 wherein the inner portion and the outer portion are two distinct regions separated by a space.

[c11] A printed circuit board according to claim 1 comprising all of the following:
(i) a majority of power supply contacts configured substantially in an extremity of said outer portion;
(ii) a majority of timing or frequency contacts configured substantially in said outer portion; and
(iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

[c12] A printed circuit board according to claim 11 wherein the inner portion and the outer portion are two distinct regions separated by a space.

[c13] A printed circuit board according to claim 1 and further comprising a majority of ground contacts configured substantially in said inner portion.